

PCN97009A Data2

Reliability Testing Summary

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|--------------------------|--------------------------------------|
| Technology: | Si Gate CMOS |
| Device Type: | XC4025E & XC4013E |
| Package Type: | HQ240 Thermally Enhanced PQFP |
| Molding Compound: | Sumitomo 7304LC/F |

| | Pre. Cond. 0.0621% 30/60% 192 Hrs. 3 V.P. 219°C | 85°C / 85% 1,000 Hrs. | Pressure Pot 96 Hrs. 121°C/2 Atm. | Temp. Cycle 542 Cys. -65°C / +150°C |
|--------------------------------------|---|---------------------------------|--|--|
| Combined Started Lot: | 1 | 1 | 1 | 1 |
| Combined Completed Lots: | 1 | 1 | 1 | 1 |
| Failures: | 0 | 0 | 0 | 0 |
| Device on Test: | 111 | 44 | 45 | 21 |
| Actual Device Hours / Cycles: | 21,312 | 44,000 | 4,320 | 11,382 |
| Mean: | 192 | 1,000 | 96 | 542 |
| Physical Dimension: | Passed | | | |
| Solderability: | Passed | | | |
| Internal Visual: | Passed | | | |
| Lead Integrity: | Passed | | | |
| Peel Test / X-Ray: | Passed | | | |